EVASOL J3-8600-KF

Sn-Ag-Cu type Lead free solder paste
RMA type、Non cleaning

<Feature>

- This solder paste is composed of true spherical lead free solder powder.
- It is superior to print for fine pitch QFP pattern.
- It has scarce slump and solder ball after soldering.
- It has high reliability of solder paste.

Characteristic

Test terms		Characteristic	Test method (based on JIS)	
Alloy composition (%)		Sn:balance, Ag:3.0, Cu:0.5	Allowable impurity level is based on JIS Z 3282 class-A	
Solidus temperature (℃)		217	DSC (Differential Scanning Calorimetry)	
Liquidus temperature (℃)		220		
Powder particle size (μm)		38～25	Reference by JIS Z 3284 Annex 1	
Flux contents (mass %)		11.4	Reference by JIS Z 3197 8.1.2	
Halide content (mass %)		0.01	Reference by JIS Z 3197 8.1.4.2.1	Reference by 2.3.35
Copper mirror test		No corrosion	Reference by JIS Z 3197 8.4.2	Reference by 2.3.32
Copper plate corrosion test		No corrosion	Reference by JIS Z 3197 8.4.1	Reference by 2.6.15
Insulation resistance test (Ω)		Testing	Reference by JIS Z 3197 8.5.3 JIS type, 85℃-90RH%, 168hr DC100V in the chamber	Reference by 2.6.3.3
Voltage-applied moisture resistance test	Insulation resistance (Ω)	Testing	Reference by JIS Z 3197 8.5.4 JIS type, 85℃-90RH%, 1000h, Applied DC48V DC100V in the chamber	
	Migration test	Testing		
Dryness test		Passed	Reference by JIS Z 3197 8.5.1	
Spreading ratio (%)		84	Reference by JIS Z 3197 8.3.1.1	
Viscosity(Pa･s)		220	Reference by JIS Z 3284 Annex 6	
Thixotropy index		0.59		
Tackiness test	Initial (N)	1.42	Reference by JIS Z 3284 Annex 9	Reference by 2.4.44
	After 24hr(N)	1.05		
Slump-in-printing	Pattern Ⅰ	0.2	Reference by JIS Z 3284 Annex 7	Reference by 2.4.35
	Pattern Ⅱ	0.2		
Slump-in-heating	Pattern Ⅰ	0.3	Reference by JIS Z 3284 Annex 8	
	Pattern Ⅱ	0.3		

＊Above values are typical values.

＊This solder paste includes non-ionic halide activator.